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PN - JP51018245 A 19760213
 PNFP - JP54008458B B 19790416
 - JP978727C C 19791030
 FI - B23K35/363&A; B23K35/363&C; H05K3/34&503Z
 FT - 5E319/AC01; 5E319/CC23; 5E319/CD01; 5E319/CD21; 5E319/CD52; 5E319/GG20
 PA - (A)
 - TAMURA KAKEN CO LTD
 IN - (A)
 - NAKAMURA KOZO
 AP - JP19740089115 19740805
 PR - JP19740089115 19740805
 DT - |

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AN - 1976-23519X [13]
 TI - Delustering [2] for soldering printed circuits - contains inorg oxide powder and/or org acid metal salt powder
 AB - An inorg. oxide fine powder and/or org. acid metal salt fine powder is/are added to a flux base consisting of rosin type resin, activator and org. solvent. The inorg. oxide may be silicic acid anhydride, clay, titanium oxide, silice gel, etc. and the org. acid metal salt may be aluminium stearate, aluminium oleate, aluminium palmitate, etc. The surface of the welded areas is delustered and non-corrosive.
 IW - DELUSTERED FLUX SOLDER PRINT CIRCUIT CONTAIN OXIDE POWDER ACID METAL SALT
 PN - JP51018245 A 19760213 DW197613
 JP54008458B B 19790416 DW197919
 ICAI - B23K35/362; B23K35/363; H05K3/34
 ICCI - B23K35/362; H05K3/34
 MC - L03-D03F L03-H04E
 DC - L03 M23
 - F55
 - V04
 PA - (TAMU-N) TAMURA KAKEN CO LTD
 AP - JP19740089115 19740805